

WHAT WE CLAIM ARE:

1. A method of manufacturing a probe unit having leads whose front portions extending beyond an edge of a substrate, the method comprising the steps of:

forming a recess in a surface layer of a substrate;

5 filling a sacrificial layer in the recess;

forming a number of leads on the surface of the substrate, the leads being disposed in parallel and extending into an area of the sacrificial layer;

forming a cut extending from a bottom surface of the substrate into the sacrificial layer; and

10 removing the sacrificial layer.

2. A method according to claim 1, wherein the sacrificial layer is made of metal, resin or inorganic material.

15 3. A method of manufacturing a probe unit having leads whose front portions extending beyond an edge of a substrate, the method comprising the steps of:

forming a through hole through a substrate;

filling a sacrificial layer in the through hole;

forming a number of leads on the surface of the substrate, the leads

20 being disposed in parallel and extending into an area of the sacrificial layer; and

removing the sacrificial layer.

4. A method according to claim 3, wherein the sacrificial layer is made of metal, resin or inorganic material.

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5. A method of manufacturing a probe unit having leads whose front portions

extending beyond an edge of a substrate, the method comprising the steps of:

(a) applying a ultraviolet ray to a partial surface area of a photosensitive etching glass substrate;

(b) forming a number of leads on the surface of the substrate, the leads being disposed in parallel and extending from a ultraviolet ray unirradiated area into a ultraviolet ray radiated area; and

(c) etching the glass substrate in the ultraviolet ray radiated area.

6. A method according to claim 5, further comprising, before said step (b), the steps of:

(x) applying a ultraviolet ray to areas over which the leads are to be formed in an area where the ultraviolet ray is not radiated, and etching the irradiated areas to form through holes; and

(y) filling the through holes with conductive members.